SUSS MICROTEC INVESTOR PRESENTATION

May 2014

DISCLAIMER

This presentation contains forward-looking statements relating to the business, financial performance and earnings of SUSS MicroTec AG and its subsidiaries and associates. Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SUSS MicroTec AG. Consequently, actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements. SUSS MicroTec AG does not intend or accept any obligation to publish updates of these forward-looking statements.

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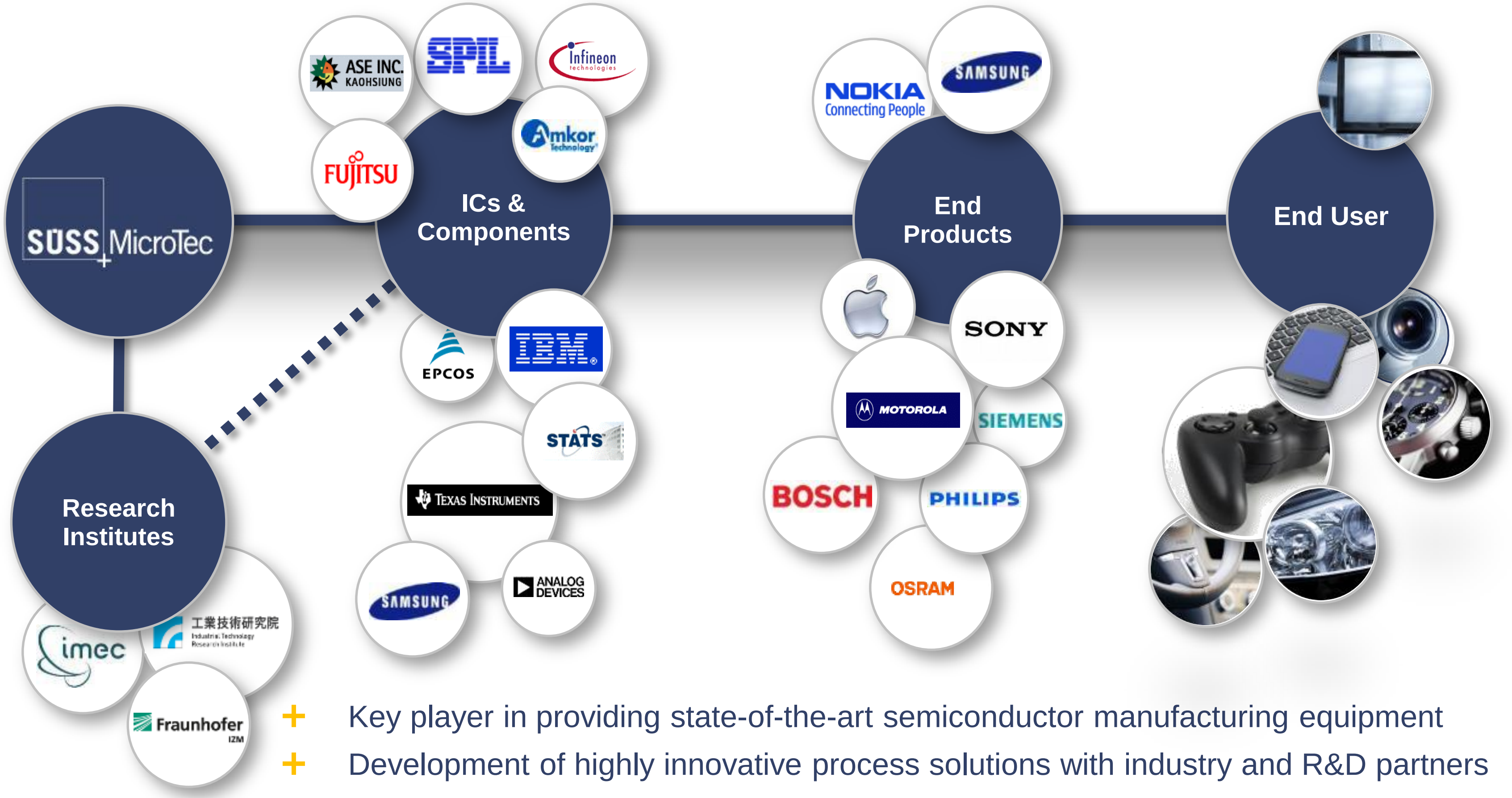
SUSS MICROTEC AT A GLANCE

SUSS MicroTec

- A global leader in manufacturing equipment for the semiconductor mid- and backend market
- Our equipment and process solutions create the micro structures that build and connect micro electronic devices
- Focused on attractive growth markets: Semiconductors, MEMS and LED
- Leading market position in target markets
- SUSS MicroTec is listed in the Prime Standard of Deutsche Boerse

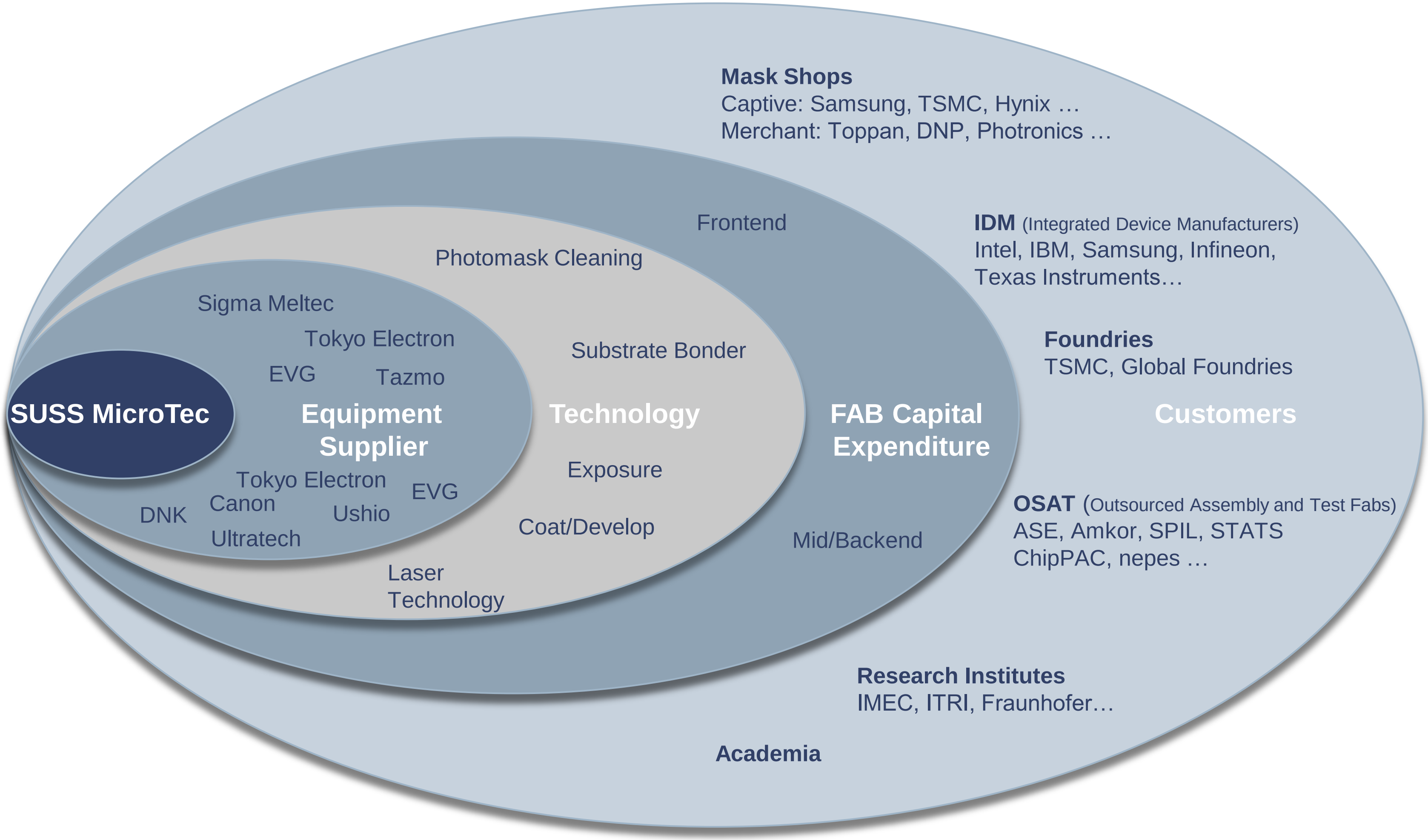
XBS300

SUSS MICROTEC IN THE VALUE CHAIN



- Key player in providing state-of-the-art semiconductor manufacturing equipment
- Development of highly innovative process solutions with industry and R&D partners
- Key components for electronic devices like cell phones, PCs and tablet computers are produced on SUSS MicroTec's equipment

THE SEMICONDUCTOR MARKET



SUSS MICROTEC – A GLOBAL PLAYER

NORTH AMERICA

- 🟦 Sunnyvale, US
- ▨ Corona, US

EUROPE

- ■ ▨ Garching, DE
- ▨ Sternenfels, DE
- ▨ Hâuterive, CH
- 🟦 Pierre-Bénite, FR
- 🟦 Coventry, UK

ASIA

- 🟦 Yokohama, JP
- 🟦 Hwaseong City, KR
- 🟦 Singapore, SG
- 🟦 Shanghai, CN
- 🟦 Hsinchu, TW

■ Headquarters
▨ Production
🟦 Sales

MAIN PRODUCTION SITES

Germany

Garching*

- SUSS MicroTec HQ
- Development/production:
  - **Mask Aligner**
  - **Bond Aligner**
- Core competencies:
  - **Exposure** (proximity exposure)
  - **Alignment**

Sternenfels*

- Development/production :
  - **Bonder**
  - **Coater and Developer**
  - **Photomask Equipment**
- Core competencies:
  - **Wet processing**
  - **Wafer bonding**

USA

Corona

- Development/production:
  - **Stepper/Scanner**
  - **Laser Processing**
- Core competencies:
  - **Exposure** (UV projection)
  - **Laser Ablation**

*Production site is owned by SUSS MicroTec

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III. Growth Opportunities

IV. Enhanced Lithography Portfolio

V. Financials

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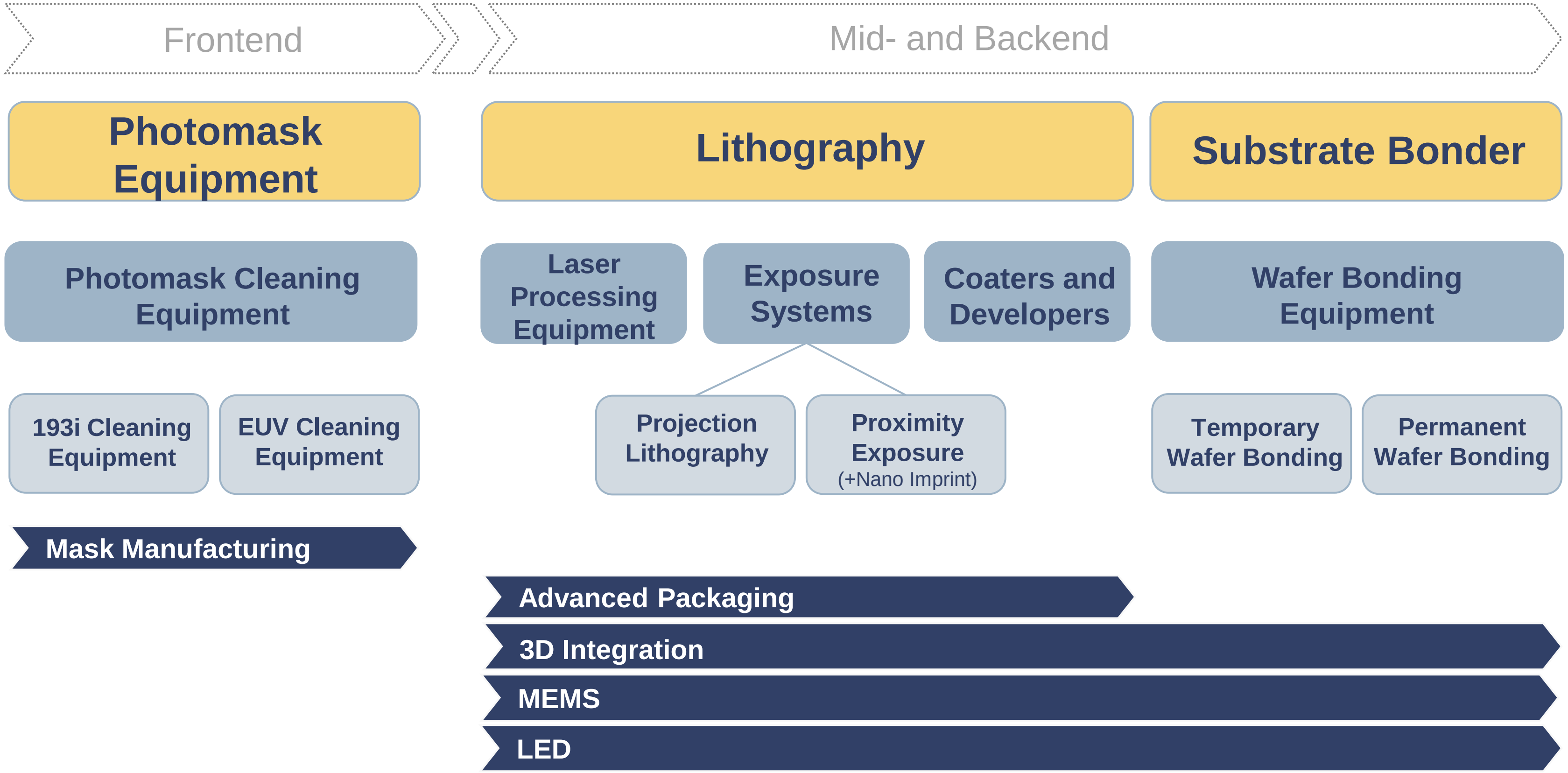
SEGMENTS, PRODUCTS AND MARKETS



Frontend

Mid- and Backend

Photomask Equipment

- Photomask Cleaning Equipment
  - 193i Cleaning Equipment
  - EUV Cleaning Equipment

Lithography

- Laser Processing Equipment
- Exposure Systems
  - Projection Lithography
  - Proximity Exposure (+Nano Imprint)
- Coaters and Developers

Substrate Bonder

- Wafer Bonding Equipment
  - Temporary Wafer Bonding
  - Permanent Wafer Bonding

Mask Manufacturing

Advanced Packaging

3D Integration

MEMS

LED

Q1 Order Entry: 4.6 € million
Q1 Sales: 6.0 € million
Q1 EBIT: 1.6 € million

Q1 Order Entry: 15.7 € million
Q1 Sales: 19.8 € million
Q1 EBIT: 1.2 € million

Q1 Order Entry: 3.1 € million
Q1 Sales: 12.0 € million
Q1 EBIT: -0.6 € million

SEGMENTS, PRODUCTS AND MARKETS

Frontend

Mid- and Backend

Photomask Equipment

Lithography

Substrate Bonder

Photomask Cleaning Equipment

Laser Processing Equipment

Exposure Systems

Coaters and Developers

Wafer Bonding Equipment

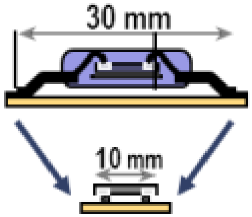
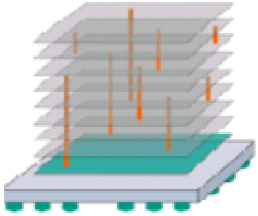
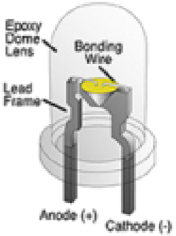
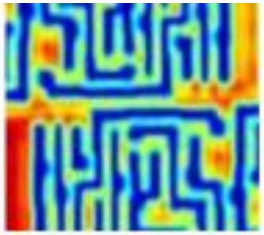
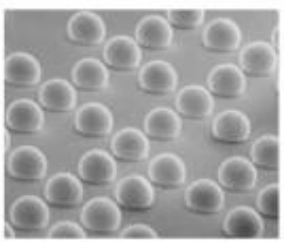
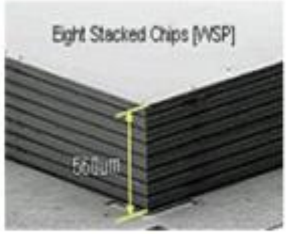
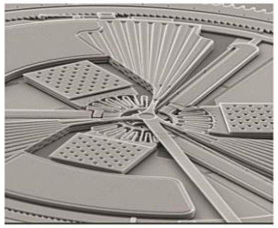
Mask Track*Pro*
(EUV mask cleaning possible)

MA/BA8 Gen3
(Mask Aligner)

ACS200 Gen3
(Spraycoater)

XBS300
(Temporary Bonder)

KEY MARKETS - OVERVIEW

Semiconductors			Sensors	Lighting
Mask Making	**Advanced Packaging**	**3D Integration**	**MEMS**	**LED**
Photomask Cleaning	Micro-Bumping	3D (TSV) Stacking	Computing, Automotive...	General Lighting, HB and UHB
	 			
		 		

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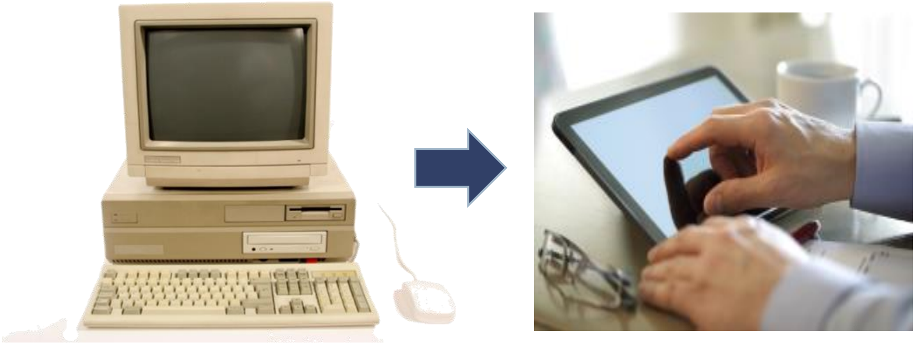
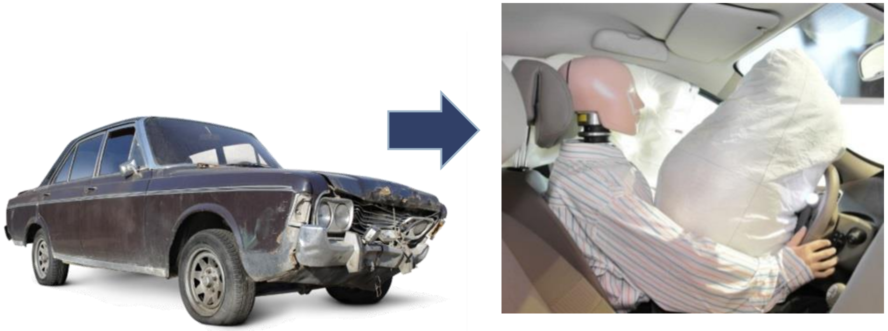
TECHNOLOGY EVOLUTION

~1985...today



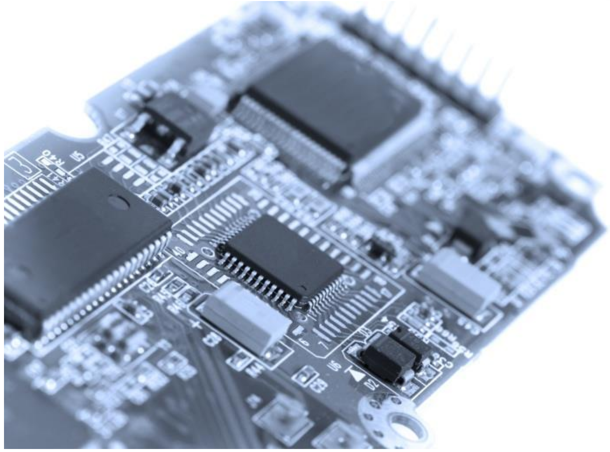
~1987...today

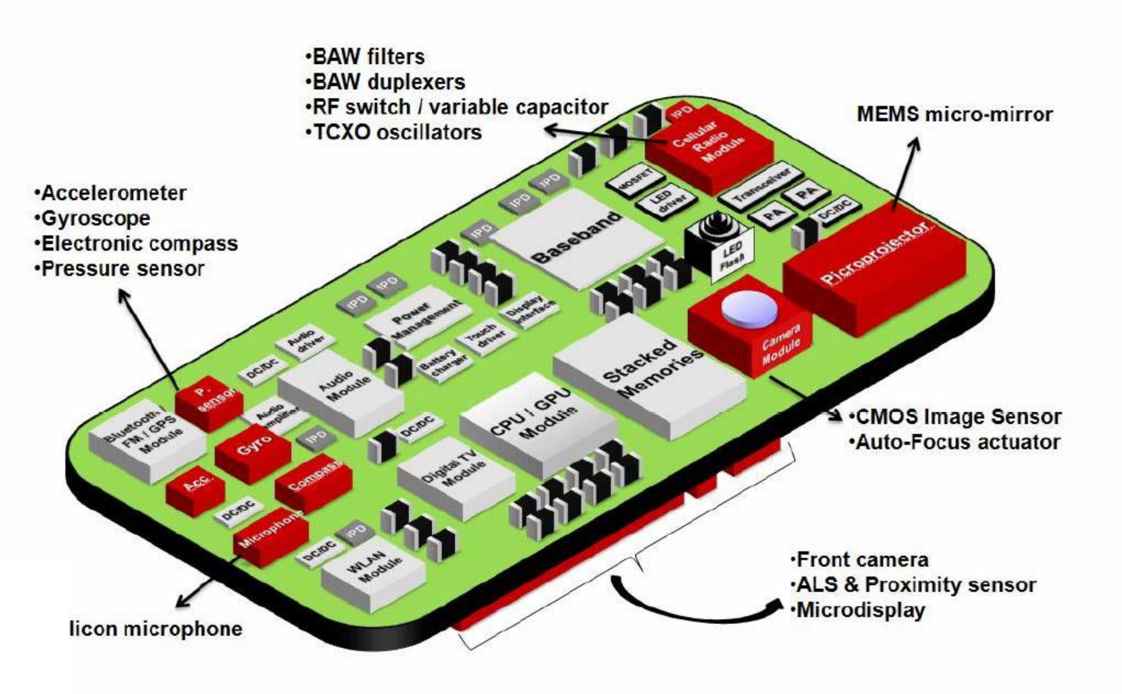
~1910...today



~1950...today

GROWTH DRIVER SMARTPHONES AND TABLETS





- BAW filters
- BAW duplexers
- RF switch / variable capacitor
- TCXO oscillators

MEMS micro-mirror

- Accelerometer
- Gyroscope
- Electronic compass
- Pressure sensor

- CMOS Image Sensor
- Auto-Focus actuator

- Front camera
- ALS & Proximity sensor
- Microdisplay

licon microphone

Source: Yole Developpement

MICROCHIPS, MEMS UND LED: BUILDING BLOCKS FOR TECHNOLOGICAL PRODUCT ADVANCEMENT

Digital Lifestyle

- The „Digital Lifestyle“ is characterized by permanent internet connectivity and convergence of media
- Mobile devices like smartphones and tablet PCs provide this capability at affordable cost
- New device generations offer higher functionality

E-Mobility

- Alternative transportation / mobility solutions are getting more traction with attractive price / performance ratios
- EVs, Hybrid-Cars, Segways, E-Bikes, but also trains drive the need for power devices and high performance Ics at the same time

Energy Efficiency

- Increased environmental awareness and rising energy cost drive the demand for energy efficient solutions i.e. solid state lighting
- Energy efficiency in industrial production
- Smart energy management in household applications

EXPECTED MARKET DEVELOPMENTS

Strong position in fast growing target markets
3D Integration / Advanced Packaging, LED and MEMS

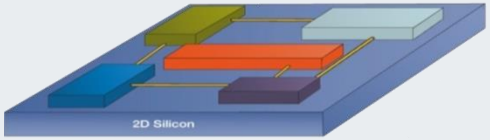
Advanced Packaging	**Wafer level packaging and flip chip is expected to remain more robust than the overall market, primarily driven by mobile devices like smart phones and tablets**
3D Integration (TSV)	**Transition to production volume in the years to come**
Compound Semiconductors	**LED, MEMS, RF, Optoelectronics, III-V Power are expected to remain robust based on smartphone and tablet growth and will drive further demand for advanced packaging solutions**

Strong fundamental segment growth

SCALING TECHNOLOGIES FROM 2D TO 3D

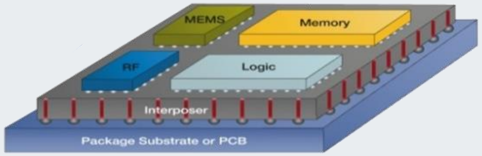
2D Packaging

- Increased performance and complexity of ICs by shrinking transistor geometry according to Moore‘s Law
- New technologies like EUV and multiple pattering allow further scaling
- Technical challenges and limitations make it increasingly more difficult and expensive to reduce the feature size



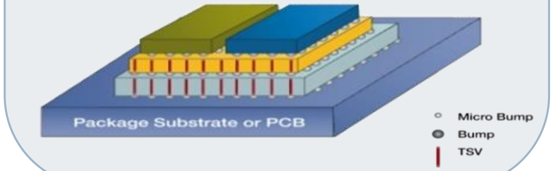
2.5D Packaging

- Combining of several (and heterogeneous) semiconductor components on an interposer addresses limitations of traditional shrinking
- Increased packaging density
- Reduced footprint
- Complementary technology to Moore‘s Law



3D Integration (TSV)

- The extension beyond the conventional shrink roadmap is called "More than Moore“
- Packaging becomes key enabler for scaling and some manufacturing value is shifting from silicon to the package
- Performance and complexity increase combined with smaller footprint
- Reduced energy consumption



SUSS MicroTec‘s equipment and process solutions enable 2D shrinking ("*Moore's Law*") and 3D stacking ("*More than Moore*")

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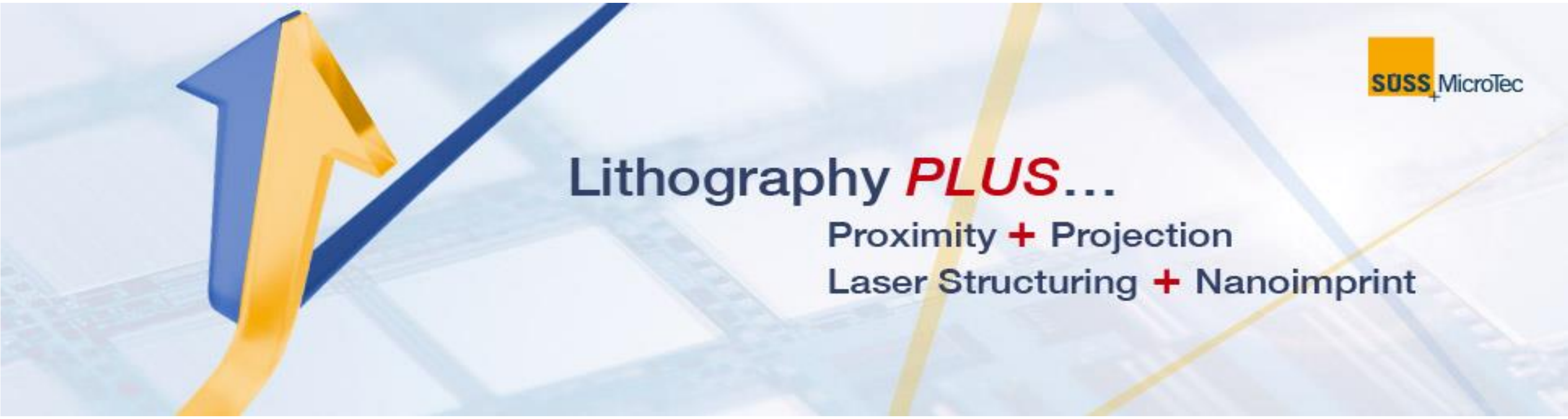
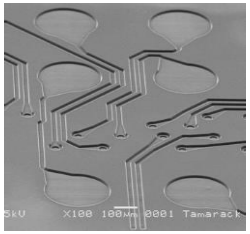
LITHOGRAPHY COMPETENCY

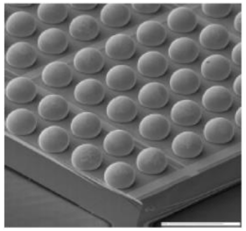
- Increasing chip performance requires the adoption of innovative lithography technologies in the semiconductor backend
- **Not one single exposure technology fits all needs at the same time**
- The newly acquired Stepper/Scanner products supplement our Mask Aligner product line and enlarges our technology portfolio by the key competencies UV-projection lithography and laser ablation
- SUSS MicroOptics S.A. adds key know how for critical lithography performance improvements



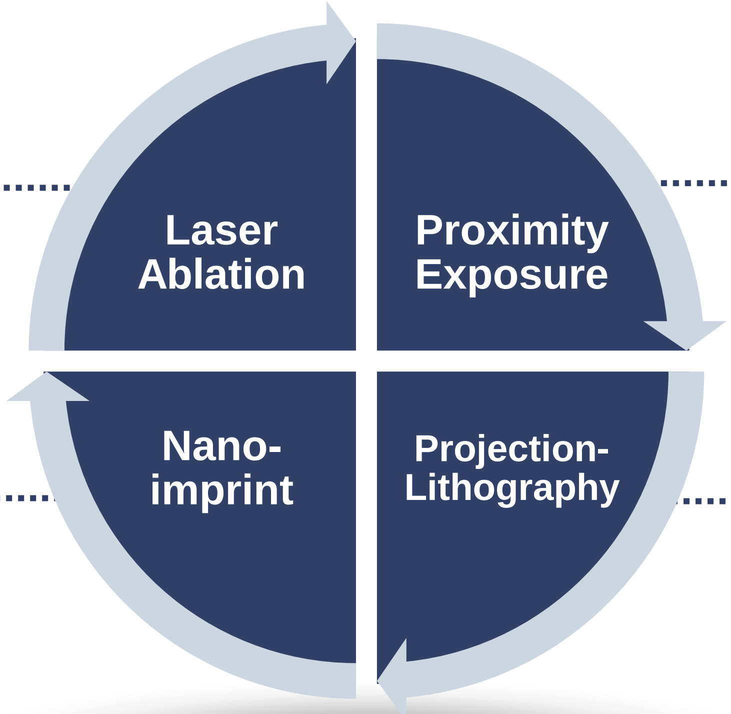
EXPOSURE SOLUTIONS



WLCSP:
Fanout WLP



Flip Chip:
Solder Bumping



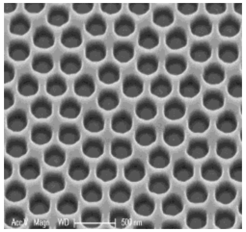
Laser Ablation

Proximity Exposure

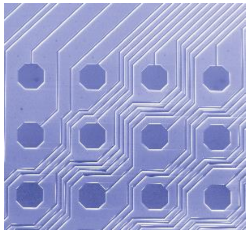
Nano-imprint

Projection-Lithography

LED:
Photonic Crystals



WLCSP:
Fine pitch RDL



Only SUSS MicroTec offers complete exposure solutions for the mid-/backend

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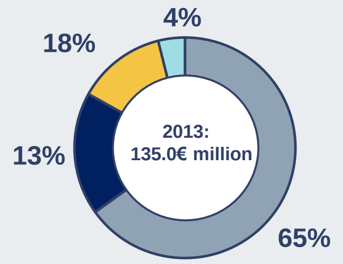
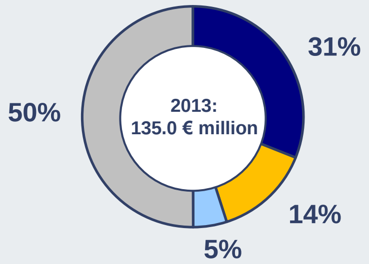
ORDER ENTRY AND SALES BY SEGMENT AND REGION 2013

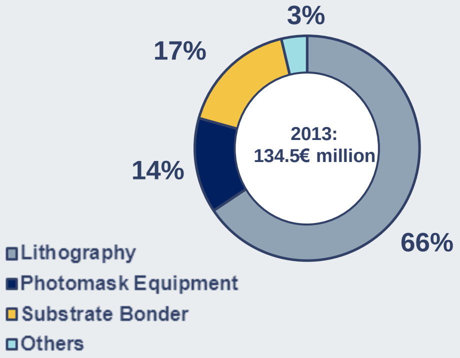
Order Entry by Segment



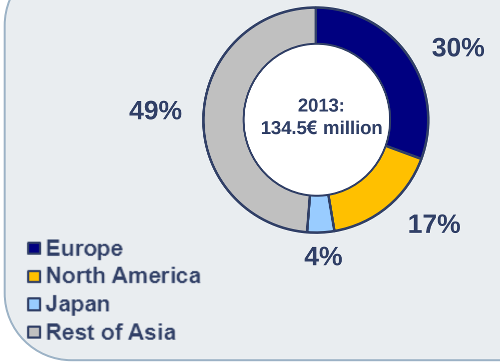
Order Entry by Region



Sales by Segment

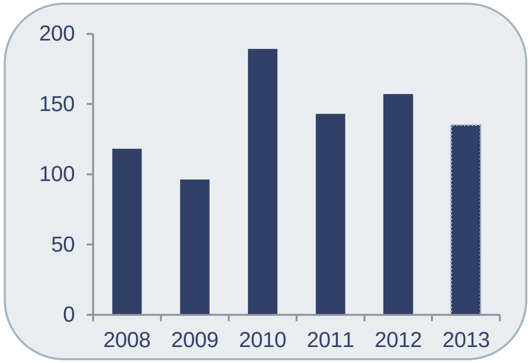


Sales by Region

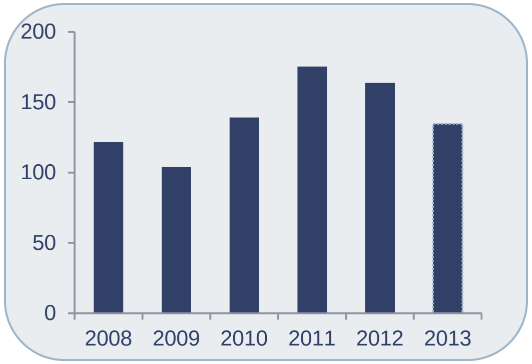


LONG TERM BUSINESS DEVELOPMENT – KEY FIGURES

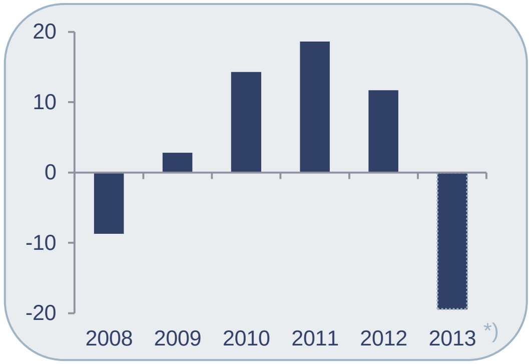
Order Entry in € million



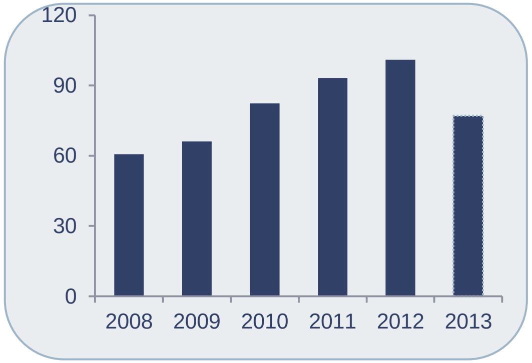
Sales in € million



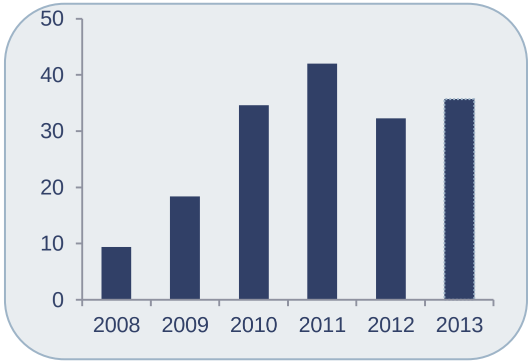
EBIT in € million



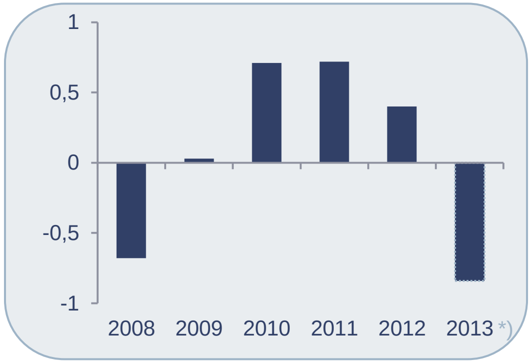
Working Capital in € million



Net cash in € million

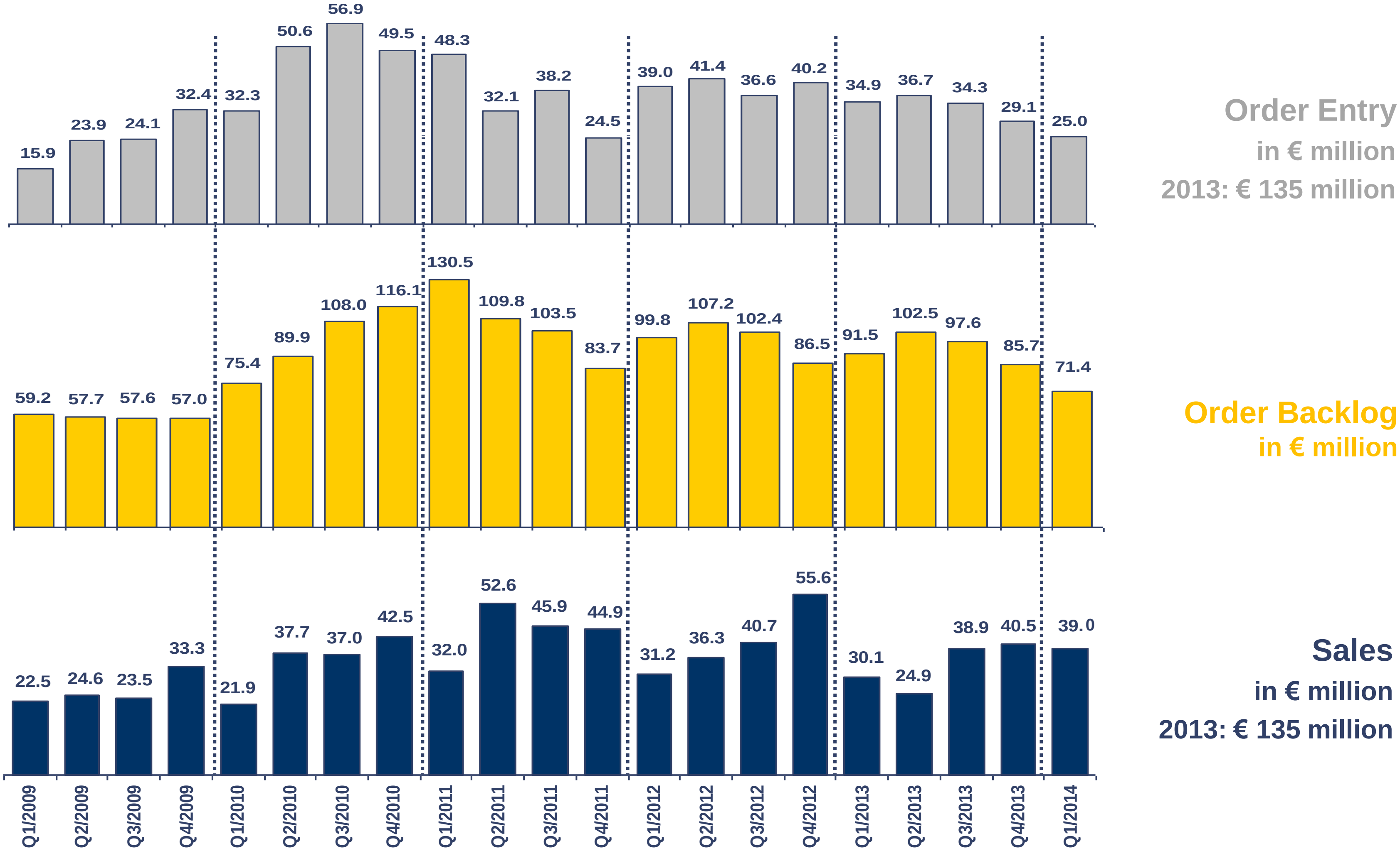


EPS in €

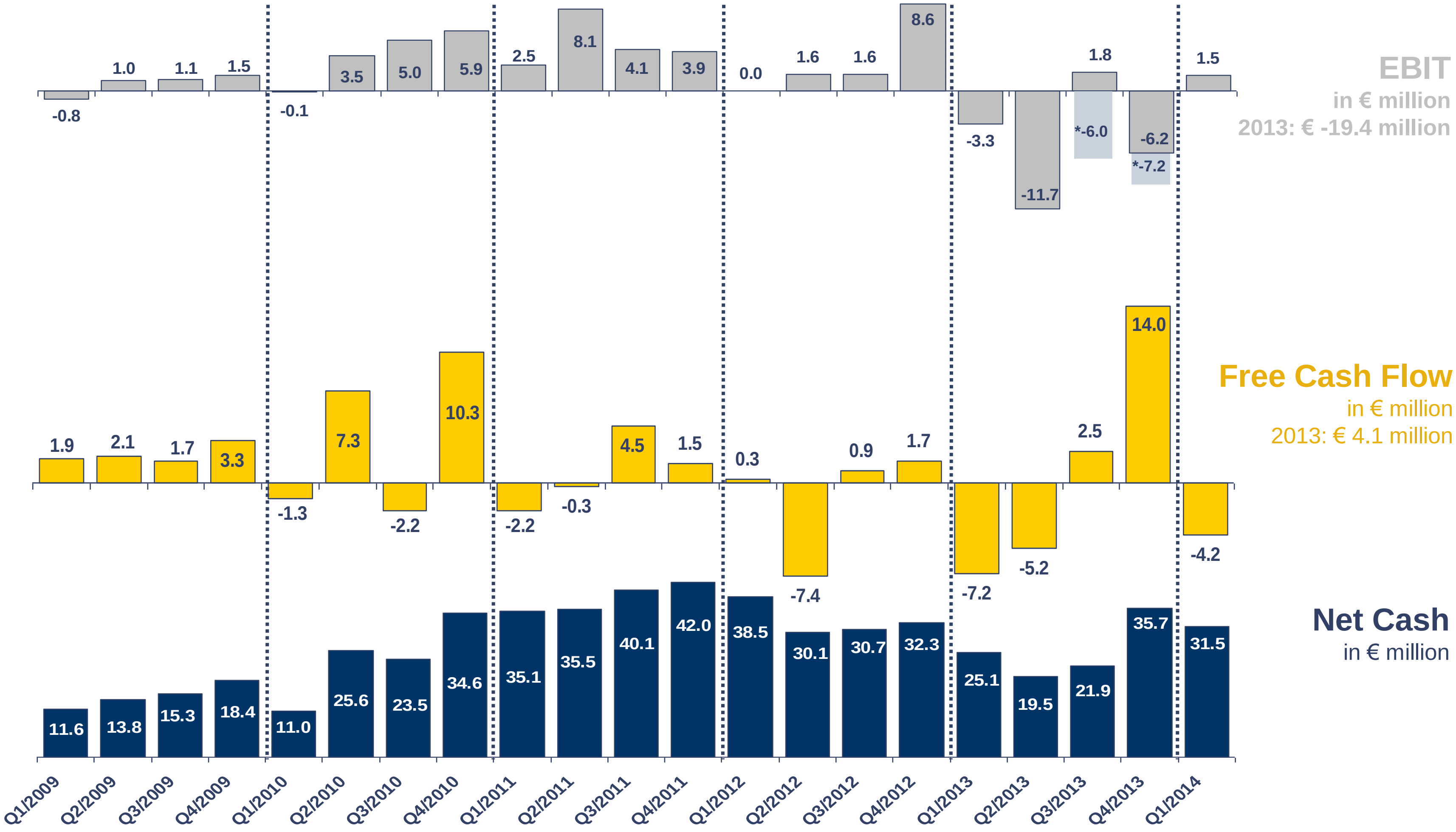


* Including a -13.2 € milion one-off effect from restructuring of the product line permanant bonding (-0,69 € per share)

LONG TERM BUSINESS DEVELOPMENT BY QUARTER



EBIT, FREE CASH FLOW AND NET CASH DEVELOPMENT



* one-off effect from refocusing product line permanent bonding

KEY FINANCIALS

in € million	Q1 2014	Q1 2013	2013	2012
Order Intake	**25.0**	**34.9**	**135.0**	**157.2**
Order Backlog 3/31	**71.4**	**91.5**	**--**	**--**
Revenue	**39.0**	**30.1**	**134.5**	**163.8**
EBIT	**1.5**	**-3.3**	**-19.4**	**11.7**
EBIT in % of Sales	*3.8%*	*-11.0%*	*-14.4%*	*7.6%*
Earnings after tax	**1.1**	**-2.5**	**-16.0**	**9.1**
EPS in €	**0.06**	**-0.13**	**-0.84**	**0.40**
Net Cash*	**31.5**	**25.1**	**35.7**	**32.3**
Free Cash Flow**	**-4.2**	**-7.2**	**4.1**	**-4.5**
Employees 3/31	**645**	**693**	**--**	**--**

* incl. stock of interest-bearing securities
** before consideration of purchased interest-bearing securities

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SUMMARY AND OUTLOOK

- **Successful restructuring in 2013**
- **Fundamental growth in target markets**
- **Strong competitive positioning: first or second in the target markets**
- **Leading equipment company in the semiconductor backend, enabling “Moore’s Law” as well as “More than Moore”**

Outlook

FY 2014:	**Sales: 135 to 145 € million** **EBIT: minus 5 to 0 million €**
Q2 2014:	**Order Intake: 30 - 40 € million**

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INVESTOR RELATIONS INFORMATION

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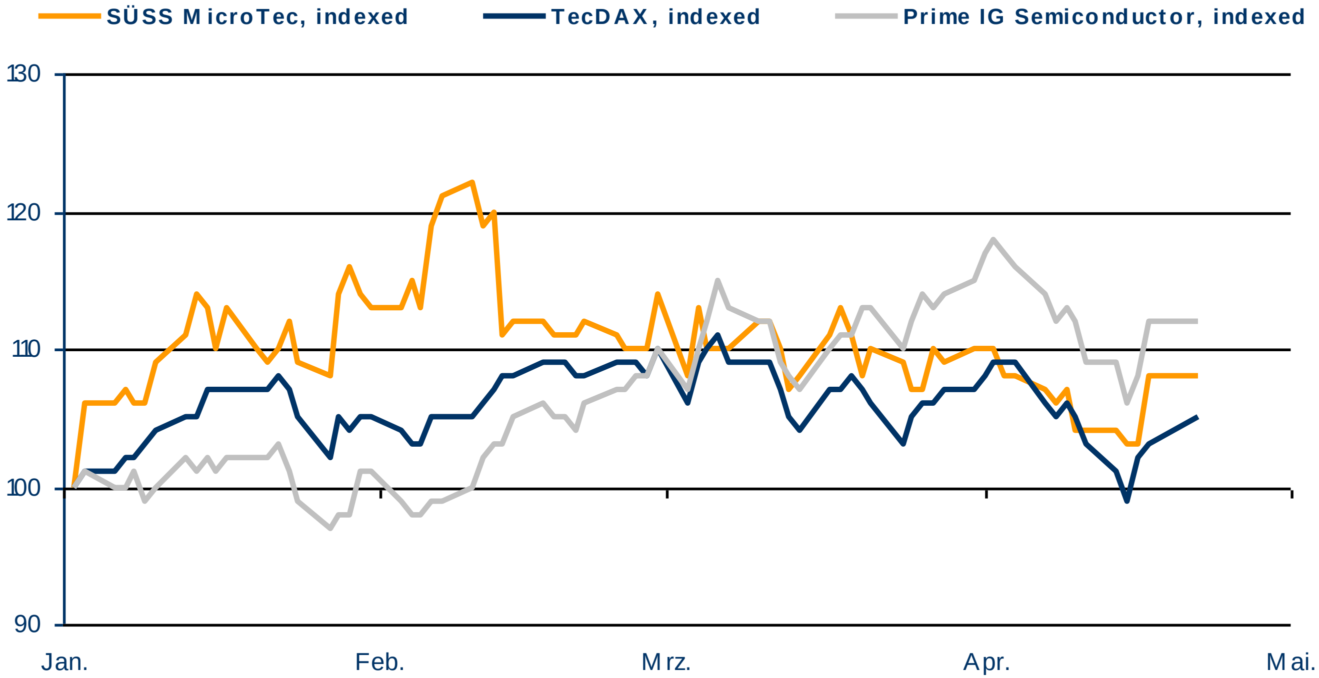
Financial Calendar 2014

Annual Report 2013	28 Mar
Quarterly Report 2014	8 May
Berenberg Investment Conference Paris	22 May
Deutsche Bank Investment Conference, Berlin	12 - 13 Jun
Shareholders’ Meeting, Haus der Bayerischen Wirtschaft, Munich	17 Jun
Interim Report 2014	7 Aug
Nine-month Report 2014	6 Nov
German Equity Forum 2014, Frankfurt am Main	24 - 26 Nov

SHARE PRICE DEVELOPMENT AND MAJOR HOLDERS

(Price of the SUSS MicroTec Share at January 2, 2014: 6.38 €)



Major Shareholders:

Credit Suisse 3.35%

BlackRock 3,23%

Henderson 5.13%

Schroders 3.1%

Vanguard 3.2%

Baillie Gifford 3.0%

Average daily trading volume January 2013 – April 2014: ~ 82,000

OUR TECHNOLOGY ENABLES SUSTAINABILITY

Equipment

- SUSS MicroTec equipment is designed to efficiently use electricity and chemicals
- ReMan, the remanufacturing operation of SUSS MicroTec takes back used equipment and refurbishes it

QUALITY +++ SERVICE +++ SUPPORT +++ RELIABILITY +++

Remanufactured by OEM

CERTIFIED

SUSS MicroTec

Applications

- 3D IC and chip scaling helps reducing energy and material consumption
- LEDs for efficient lighting solutions
- MEMS applications improve performance of mobile devices and conserve energy
- Shift to renewable energies requires more power devices and high-performance ICs (e.g. for solar and wind power systems)
- Laser Ablation in lieu of photolithography (seed layer removal)

Initiatives

- Partner company of VDMA BlueCompetence initiative, a network of equipment providers in Germany, who are following a sustainable business approach
- Innovative lighting solution in Sternenfels
- Improved climatization system of cleanrooms
- Paperless invoice system

BLUECOMPETENCE
Alliance Member

Partner der Nachhaltigkeitsinitiative
des Maschinen- und Anlagenbaus